

Abstract

Described herein is a probe card assembly providing signal paths for conveying high frequency signals between bond pads of an integrated circuit (IC) and an IC tester.

- 5 The frequency response of the probe card assembly is optimized by appropriately distributing, adjusting and impedance matching resistive, capacitive and inductive impedance values along the signal paths so that the interconnect system behaves as an appropriately tuned
- 10 Butterworth or Chebyshev filter.